

NAND Flash Code Information(1/3)

Last Updated : April 2008

<u>K</u>	<u>9</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>-</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18

1. Memory (K)

2. NAND Flash : 9

3. Small Classification

(SLC : Single Level Cell, MLC : Multi Level Cell,

SM : SmartMedia, S/B : Small Block)

1 : SLC 1 Chip XD Card

2 : SLC 2 Chip XD Card

3 : 4bit MLC Mono

4 : SLC 4 Chip XD Card

5 : MLC 1 Chip XD Card

6 : MLC 2 Chip XD Card

7 : SLC moviNAND

8 : MLC moviNAND

9 : 4bit MLC ODP

A : 3bit MLC MONO

B : 3bit MLC DDP

C : 3bit MLC QDP

F : SLC Normal

G : MLC Normal

H : MLC QDP

K : SLC Die Stack

L : MLC DDP

M : MLC DSP

N : SLC DSP

O : 3bit MLC ODP

P : MLC ODP

Q : SLC ODP

T : SLC SINGLE (S/B)

W : SLC 4 Die Stack

4~5. Density

12 : 512M	16 : 16M	28 : 128M
32 : 32M	40 : 4M	56 : 256M
64 : 64M	80 : 8M	1G : 1G
2G : 2G	4G : 4G	8G : 8G
AG : 16G	BG : 32G	CG : 64G
DG : 128G	EG : 256G	LG : 24G
NG : 96G	ZG : 48G	00 : NONE

6. Technology

0 : Normal (x8)

C : Catridge SIP

M : moviNAND

S : eSSD

1 : Normal (x16)

D : DDR

P : moviMCP

7. Organization

0 : NONE

6 : x16

8 : x8

8. Vcc

A : 1.65V~3.6V

C : 5.0V (4.5V~5.5V)

E : 2.3V~3.6V

Q : 1.8V (1.7V ~ 1.95V)

U : 2.7V~3.6V

W : 2.7V~5.5V, 3.0V~5.5V

B : 2.7V (2.5V~2.9V)

D : 2.65V (2.4V ~ 2.9V)

R : 1.8V (1.65V~1.95V)

T : 2.4V~3.0V

V : 3.3V (3.0V~3.6V)

0 : NONE

9. Mode

0 : Normal

1 : Dual nCE & Dual R/nB

3 : Tri /CE & Tri R/B

4 : Quad nCE & Single R/nB

5 : Quad nCE & Quad R/nB

9 : 1st block OTP

A : Mask Option 1

L : Low grade

10. Generation

M : 1st Generation

A : 2nd Generation

B : 3rd Generation

C : 4th Generation

D : 5th Generation

E : 6th Generation

Y : 25th Generation

Z : 26th Generation

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1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18

11. "—"

12. Package

A : COB
 B : FBGA (Halogen-Free, Lead-Free)
 C : CHIP BIZ D : 63-TBGA
 F : WSOP (Lead-Free) G : FBGA
 H : TBGA (Lead-Free)
 I : ULGA (Lead-Free) (12*17)
 J : FBGA (Lead-Free)
 L : ULGA (Lead-Free) (14*18)
 M : TLGA N : TLGA2
 P : TSOP1 (Lead-Free)
 Q : TSOP2 (Lead-Free)
R : 56-TSOP1 (Lead-Free)
 S : TSOP1 (Halogen-Free, Lead-Free)
 T : TSOP2 U : COB (MMC)
 V : WSOP W : Wafer
 Y : TSOP1 Z : WELP (Lead-Free)

13. Temp

C : Commercial I : Industrial
 S : SmartMedia
 B : SmartMedia BLUE
 0 : NONE (Containing Wafer, CHIP, BIZ, Exception handling code)

14. Customer Bad Block

B : Include Bad Block
 D : Daisychain Sample
K : Special Handling
 L : 1~5 Bad Block
 N : ini. 0 blk, add. 10 blk
 S : All Good Block
 0 : NONE (Containing Wafer, CHIP, BIZ, Exception handling code)

15. Pre-Program Version

0 : None
 Serial (1~9, A~Z)

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1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18

16. Packing Type

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
Component	TAPE & REEL	T
	Other (Tray, Tube, Jar)	0 (Number)
	Stack	S
Module	MODULE TAPE & REEL	P
	MODULE Other Packing	M

17~18. Customer "Customer List Reference"